

广东星坤科技股份有限公司

日期

文件工程章

MARK	DESCRIPTION	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES
Δ*					ANGLAR ±5°
Δx					L ≤ 4 ±0.2
Δx					4 < L ≤ 16 ±0.3
					16 < L ≤ 63 ±0.4
					L > 63 ±0.5
REVISIONS					
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DSND		SCALE: N/A	MODEL TYPE:
DWN		VIEW:	PART NO.: X1304WWS-52X-LPV10
CHKD		UNIT: mm/in	DWG NO.:
APPD		SIZE: A4	X-X1304WWS-52X-LPV10
		WEIGHT	SHEET
		1/1	REVISION
			A0

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NOTES 注释:

1. MATERIAL 材料:

HOUSING 外壳: THERMOPLASTIC, HIGH TEMP.,
UL94V-0; BLACK COLOR

CONTACTS 触点: COPPER ALLOY.

PEGS 螺钉: COPPER ALLOY.

2. FINISH 饰面:

CONTACT 触点: SELECTIVE GOLD PLATING ON CONTACT AREA.
100μ" MIN. MATTE TIN PLATING ON SOLDER TAILS,
50μ" MIN. NICKEL UNDERPLATING OVERALL.

PEGS 螺钉: 120u" MIN. MATTE-TIN OVER 50u" MIN. NICKEL.

X1304 W V S - 52 X - LP V10

① ② ③ ④ ⑤ ⑥ ⑦ ⑧

① Series Number

② Terminal form: W-Wafer

③ Welding Board Angle : V-Stright Angle 180°

④ Welding Way: S-SMT

⑤ No. of Pins: 52 PIN

⑥ HEIGHT: A 4.0mm; B 5.2mm; C 5.6mm; D 6.8mm;
E 7.0mm; F 8.0mm; G 9.0mm; H 9.9mm

⑦ Plastic material: LP-LCP UL94V-0

⑧ Contact Plating: V01-Gold Flash
V10-Gold 10 u"
V30-Gold 30 u"

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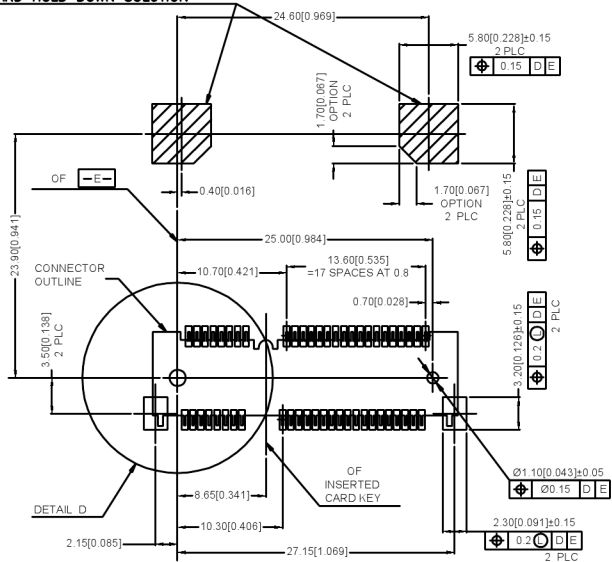
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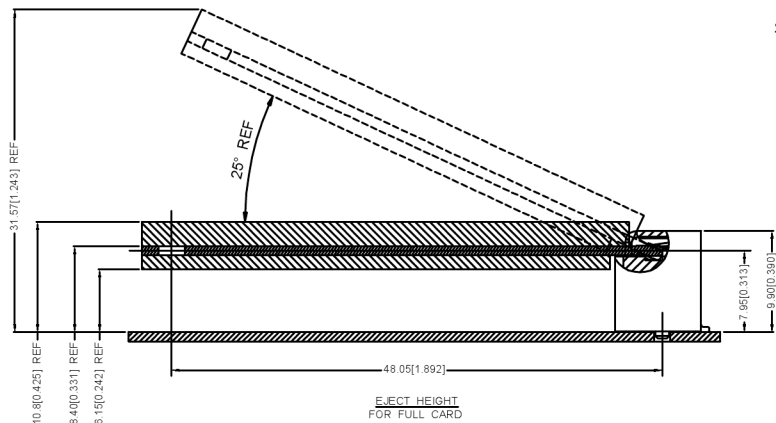
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XKB INDUSTRIAL PRECISION CO., LIMITED		SHEET 1/1
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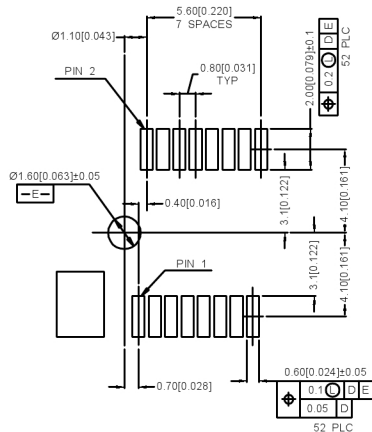
COMPONENT KEEP OUT AREA FOR
CARD HOLD DOWN SOLUTION



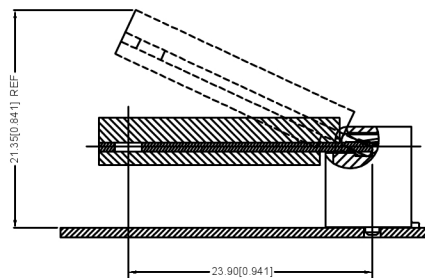
—D— IS THE TOP SURFACE OF PCB.
RECOMMENDED P.C. BOARD PATTERN LAYOUT
FOR HALF CARD CONNECTOR
(TOP VIEW)



EJECT HEIGHT
FOR FULL CARD

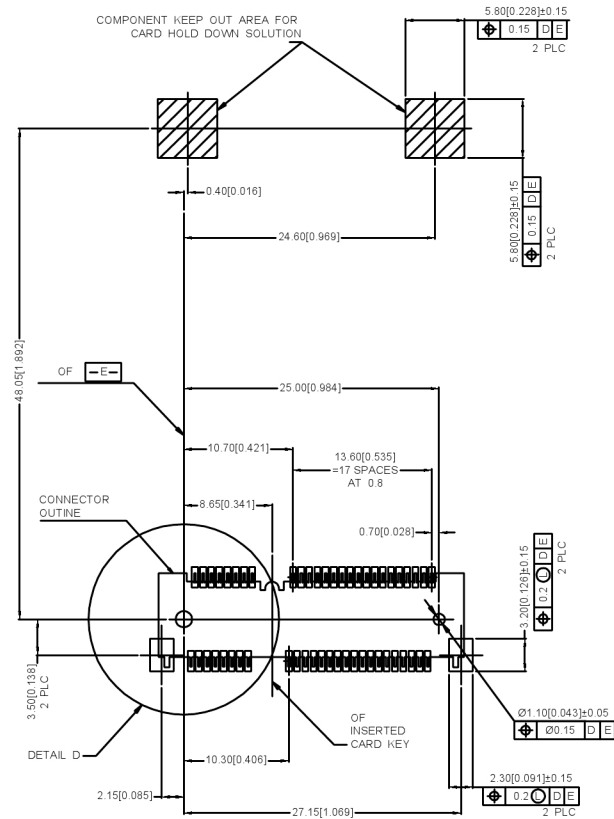


DETAIL D
SCALE 2:1



EJECT HEIGHT
FOR HALF CARD

COMPONENT KEEP OUT AREA FOR
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Δ建	日期
Δ改	日期
ΔX	
MARK	DESCRIPTION

DESCRIPTION

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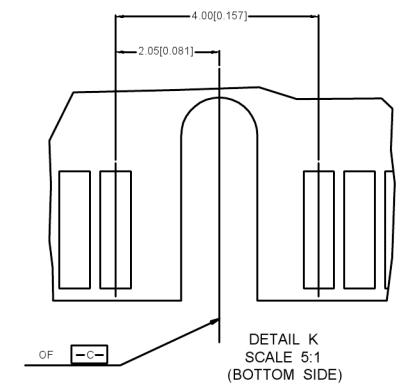
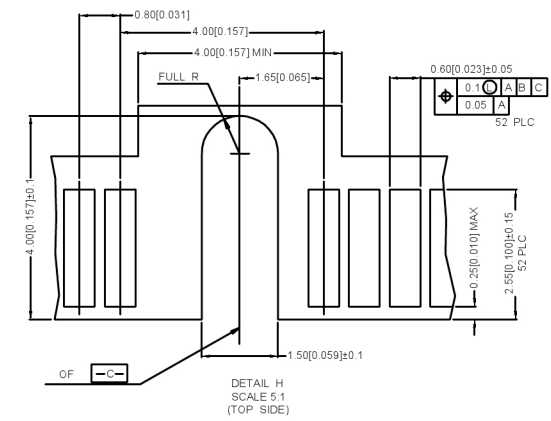
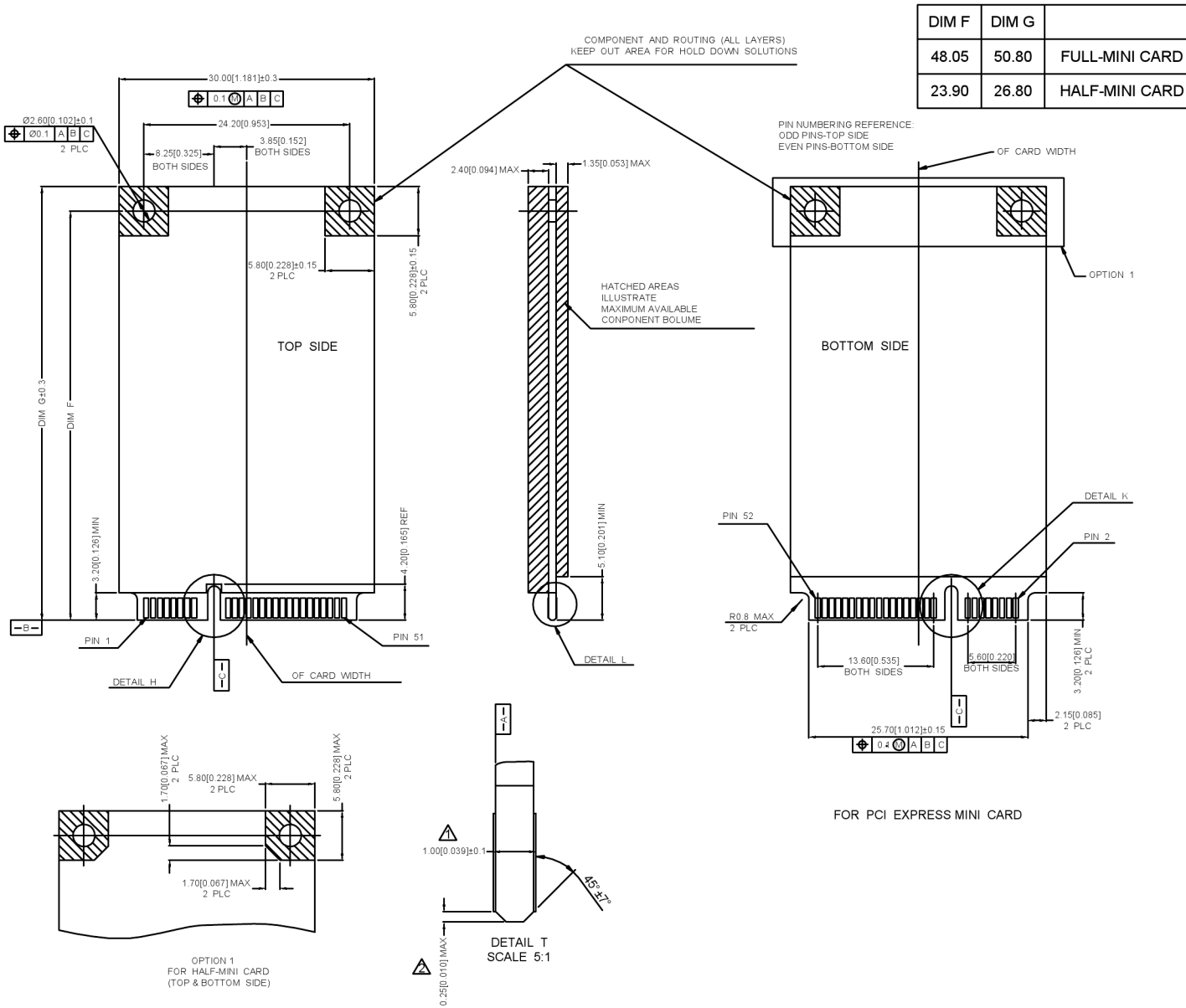
UNSPECIFIED TOLERANCES

XKLB

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XKB INDUSTRIAL PRECISION CO., LIMITED

WEIGHT	SHEET	REVISION
	1/1	A0



NOTES 注释:

- △ CARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR METALLIZATION.
卡片厚度适用于所有接线片，包括电镀和/或金属化。
- △ EDGE BEVEL MUST BE PRESENT AND FREE OF CUTTING CONTACT MATERIALS JITTERS FROM AND PCB
边缘斜面必须均匀且无切割接触材料毛刺和PCB

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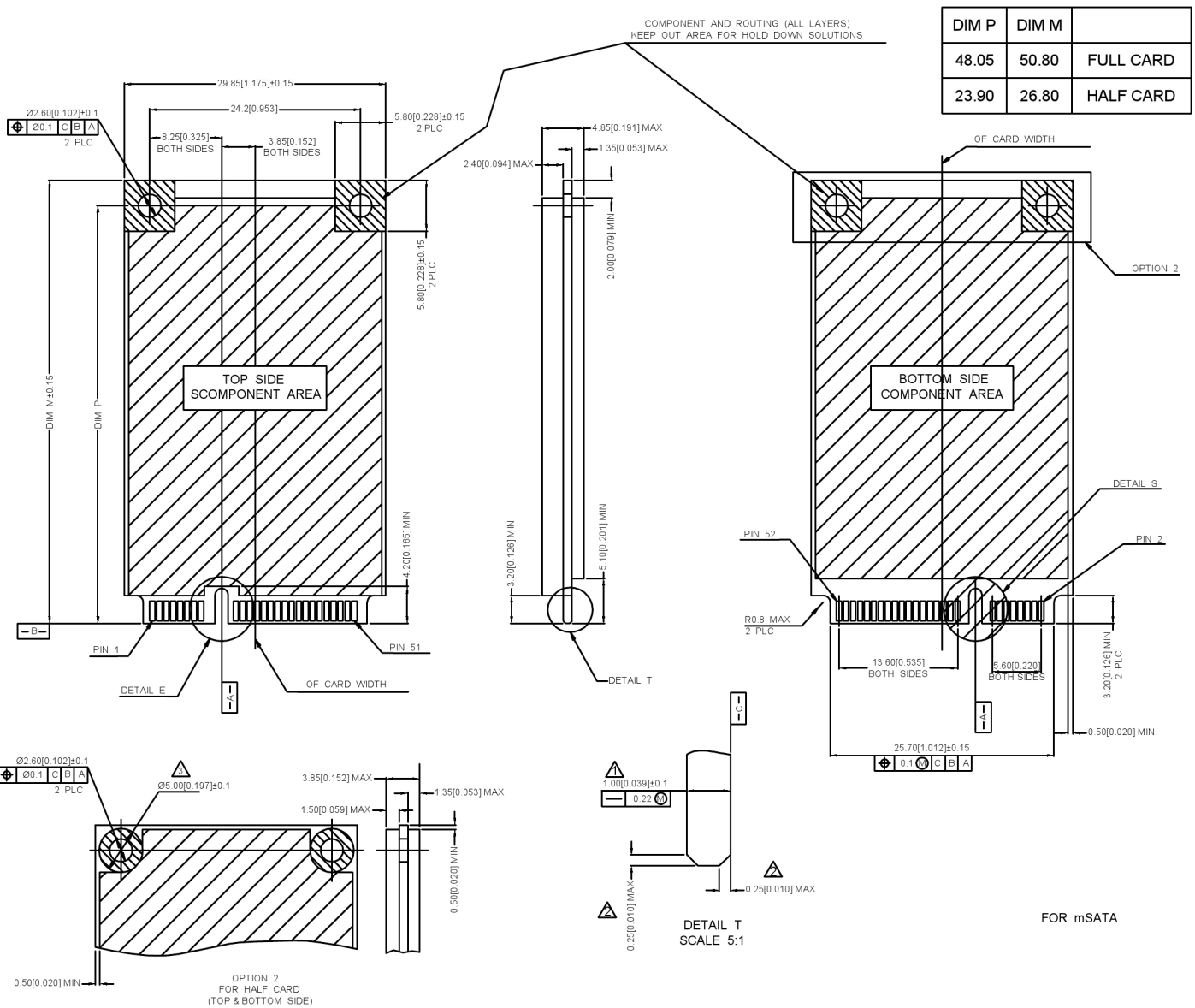
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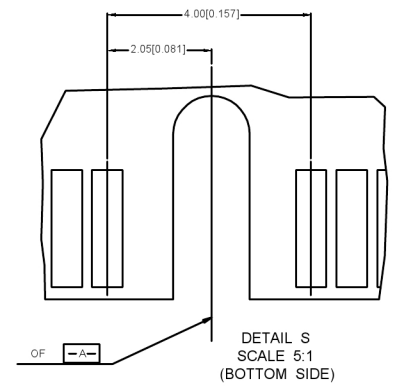
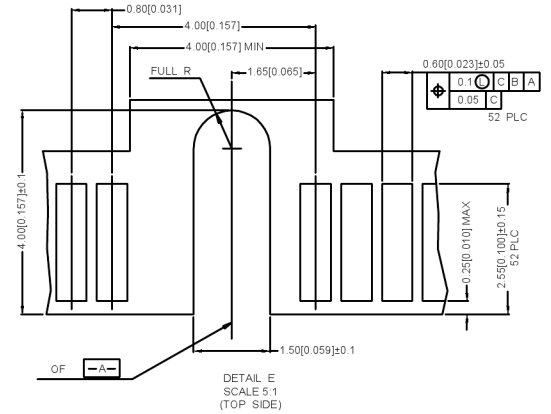


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DIM P	DIM M	
48.05	50.80	FULL CARD
23.90	26.80	HALF CARD



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 - △ EDGE BEVEL MUST BE IPRESENT AND FREE OF CUTTING CONTACT MATERIALS BURRS FROM AND PCB
边缘斜面必须均匀且无切割接触材料毛刺和PCB
 - △ COMPONENT AND ROUTING (TOP/BOTTOM LAYER) KEEP OUT AREA FOR HOLD DOWN SOLUTIONS.
元件和布线(顶层/底层)为压紧解决方案留出区域

广东星坤科技股份有限公司

姓名: _____ 日期: _____
 审核: _____
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